



Rigid PCB Capacity

Process capability for rigid FR4 printed circuit boards from 1 to 16 layers.

Technical Specification

ITEM	TECHNICAL SPECIFICATION
Layer count	1 to 16 layers
Maximum panel dimension	450 x 660 mm (18 x 26 in)
Minimum board thickness	4 layers 0.40 mm (16 mil) / 6 layers 1.00 mm (40 mil) / 8 layers 1.20 mm (48 mil)
Minimum trace width	0.075 mm (3 mil)
Minimum trace space	0.075 mm (3 mil)
Minimum finished hole	0.20 mm (8 mil)
Plated hole wall thickness	0.025 mm (1 mil)
Plated hole diameter tolerance	±0.075 mm (3 mil)
Non-plated hole diameter tolerance	±0.05 mm (2 mil)
Hole position tolerance	±0.05 mm (2 mil)
Outline dimension tolerance	±0.10 mm (4 mil)
Minimum solder bridge	0.10 mm (4 mil)
Warpage	≤0.75%
Isolation resistance	>10 ¹² Ω at normal condition
Hole resistance	<300 Ω at normal condition
Flammability rating	94V-0 self-extinguishing
Open / short test voltage	50 to 300 V

Surface Finishes Available

- **Lead-free HASL** — lowest cost, long shelf life, suitable down to roughly 0.5 mm component pitch.
- **Immersion nickel gold** — flat surface for BGA and fine pitch SMD, does not oxidise in storage.
- **Electroplated nickel gold** — hard contact surface for edge fingers, switch contacts and wire bonding.

Verification Before Shipping

- Open and short test at 50 to 300 V on every board.
- Hole resistance verified below 300 Ω at normal condition.
- Isolation resistance verified above 10¹² Ω at normal condition.
- Inner layers inspected before lamination.

Lead time, minimum order quantity and IPC class level are not published and are marked **TBC**. They are confirmed in writing with each quotation.

